	Hits	Search Text	DBs
26	13	((resist or photoresist) same pattern) and ((pattern or hole or via or (line near6 space)) same (aspect near5 ratio) same LSI) and ((resist near4 pattern) same (thicken$4 or improv$4 or enhanc$4 or coat$4 or top$4coat$4) same (heat$4 or bak$4) same (thickness or nm or micron))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
27	0	((resist or photoresist) same pattern) and ((variation or var$4) same (resist or photoresist) same (pattern or via or hole or trench$3) same (striat$6 or fish$3eyes or roughness or irregularit$4 or uneven$5) same (heat$4 or bak$4 or anneal$4)) and ((pattern or hole or via or (line near6 space)) same (aspect near5 ratio) same LSI)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
28	86	((resist or photoresist) same pattern) and ((variation or var$4) same (resist or photoresist) same (pattern or via or hole or trench$3) same (striat$6 or fish$3eyes or roughness or irregularit$4 or uneven$5) same (heat$4 or bak$4 or anneal$4))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
29	86	S28 NOT S26	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB